DISCRETE SEMICONDUCTORS

DATA SHEET

PDTC143T series NPN resistor-equipped transistors; R1 = 4.7 k Ω , R2 = open

Product data sheet Supersedes data of 2004 Apr 06 2004 Aug 06



NPN resistor-equipped transistors; R1 = 4.7 k Ω , R2 = open

PDTC143T series

FEATURES

- Built-in bias resistors
- · Simplified circuit design
- Reduction of component count
- · Reduced pick and place costs.

APPLICATIONS

- General purpose switching and amplification
- · Inverter and interface circuits
- · Circuit applications.

QUICK REFERENCE DATA

SYMBOL	PARAMETER	TYP.	MAX.	UNIT
V_{CEO}	collector-emitter voltage	_	50	V
Io	output current (DC)	_	100	mA
R1	bias resistor	4.7	_	kΩ
R2	open	_	_	_

DESCRIPTION

NPN resistor-equipped transistor (see "Simplified outline, symbol and pinning" for package details).

PRODUCT OVERVIEW

TYPE NUMBER	PACI	KAGE	MARKING CODE	DND COMPLEMENT	
ITPE NUMBER	PHILIPS	PHILIPS EIAJ		PNP COMPLEMENT	
PDTC143TE	SOT416	SC-75	40	PDTA143TE	
PDTC143TEF	SOT490	SC-89	11	PDTA143TEF	
PDTC143TK	SOT346	SC-59	52	PDTA143TK	
PDTC143TM	SOT883	SC-101	DM	PDTA143TM	
PDTC143TS	SOT54 (TO-92)	SC-43	TC143T	PDTA143TS	
PDTC143TT	SOT23	_	*33 ⁽¹⁾	PDTA143TT	
PDTC143TU	SOT323	SC-70	*52 ⁽¹⁾	PDTA143TU	

Note

^{1. * =} p: Made in Hong Kong.

^{* =} t: Made in Malaysia.

^{* =} W: Made in China.

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PDTC143T series

SIMPLIFIED OUTLINE, SYMBOL AND PINNING

TYPE NUMBER	CIMPLIFIED OUTLINE AND CYMPOL		PINNING
TYPE NUMBER	SIMPLIFIED OUTLINE AND SYMBOL	PIN	DESCRIPTION
PDTC143TS	1 R1 R1 3 MAM361	1 2 3	base collector emitter
PDTC143TE PDTC143TEF PDTC143TK PDTC143TT PDTC143TU	3 1 R1 2 Top view MDB270	1 2 3	base emitter collector
PDTC143TM	2 R1 3 Bottom view MHCS07	1 2 3	base emitter collector

NPN resistor-equipped transistors; R1 = 4.7 k Ω , R2 = open

PDTC143T series

ORDERING INFORMATION

TYPE NUMBER		PACKAGE						
ITPE NUMBER	NAME	DESCRIPTION	VERSION					
PDTC143TE	_	plastic surface mounted package; 3 leads	SOT416					
PDTC143TEF	_	plastic surface mounted package; 3 leads	SOT490					
PDTC143TK	_	 plastic surface mounted package; 3 leads 						
PDTC143TM	_	leadless ultra small plastic package; 3 solder lands; body $1.0 \times 0.6 \times 0.5$ mm	SOT883					
PDTC143TS	_	plastic single-ended leaded (through hole) package; 3 leads	SOT54					
PDTC143TT	-	plastic surface mounted package; 3 leads	SOT23					
PDTC143TU	_	plastic surface mounted package; 3 leads	SOT323					

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CBO}	collector-base voltage	open emitter	_	50	V
V _{CEO}	collector-emitter voltage	open base	_	50	V
V _{EBO}	emitter-base voltage	open collector	_	5	V
I _O	output current (DC)		_	100	mA
I _{CM}	collector current		_	100	mA
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C			
	SOT54	note 1	_	500	mW
	SOT23	note 1	_	250	mW
	SOT346	note 1	_	250	mW
	SOT323	note 1	_	200	mW
	SOT490	notes 1 and 2	_	250	mW
	SOT883	notes 2 and 3	_	250	mW
	SOT416	note 1	_	150	mW
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C
T _{amb}	operating ambient temperature		-65	+150	°C

Notes

- 1. Refer to standard mounting conditions.
- 2. Reflow soldering is the only recommended soldering method.
- 3. Refer to SOT883 standard mounting conditions; FR4 with 60 μm copper strip line.

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PDTC143T series

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th(j-a)}	thermal resistance from junction to ambient	in free air		
	SOT54	note 1	250	K/W
	SOT23	note 1	500	K/W
	SOT346	note 1	500	K/W
	SOT323	note 1	625	K/W
	SOT490	notes 1 and 2	500	K/W
	SOT883	notes 2 and 3	500	K/W
	SOT416	note 1	833	K/W

Notes

- 1. Refer to standard mounting conditions.
- 2. Reflow soldering is the only recommended soldering method.
- 3. Refer to SOT883 standard mounting conditions; FR4 with 60 μm copper strip line.

CHARACTERISTICS

 T_{amb} = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I _{CBO}	collector-base cut-off current	$V_{CB} = 50 \text{ V}; I_E = 0 \text{ A}$	_	_	100	nA
I _{CEO}	collector-emitter cut-off current	$V_{CE} = 30 \text{ V}; I_B = 0 \text{ A}$	_	_	1	μΑ
		$V_{CE} = 30 \text{ V}; I_{B} = 0 \text{ A}; T_{j} = 150 ^{\circ}\text{C}$	_	_	50	μΑ
I _{EBO}	emitter-base cut-off current	$V_{EB} = 5 \text{ V}; I_{C} = 0 \text{ A}$	_	_	100	nA
h _{FE}	DC current gain	$V_{CE} = 5 \text{ V}; I_{C} = 1 \text{ mA}$	200	_	_	
V _{CEsat}	collector-emitter saturation voltage	$I_C = 5 \text{ mA}$; $I_B = 0.25 \text{ mA}$	_	_	100	mV
R1	input resistor		3.3	4.7	6.1	kΩ
Сс	collector capacitance	$I_E = I_e = 0 \text{ A}; V_{CB} = 10 \text{ V};$ f = 1 MHz	_	_	2.5	pF

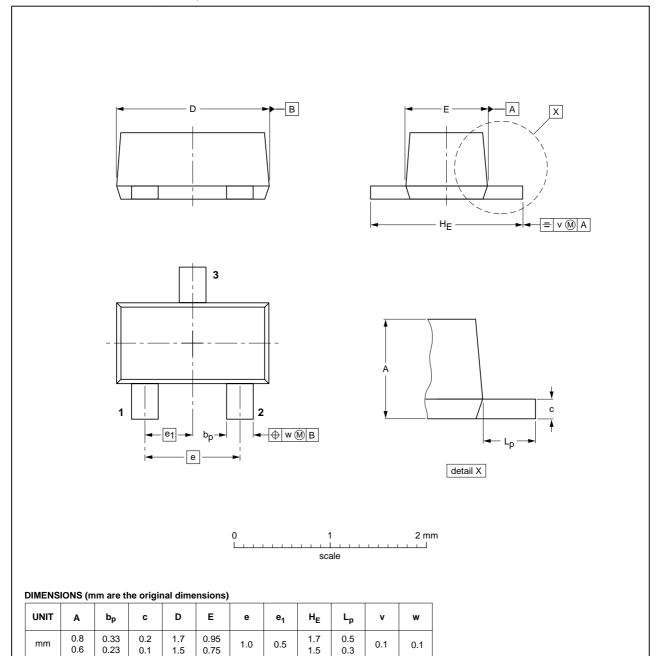
NPN resistor-equipped transistors; R1 = 4.7 k Ω , R2 = open

PDTC143T series

PACKAGE OUTLINES

Plastic surface-mounted package; 3 leads

SOT490



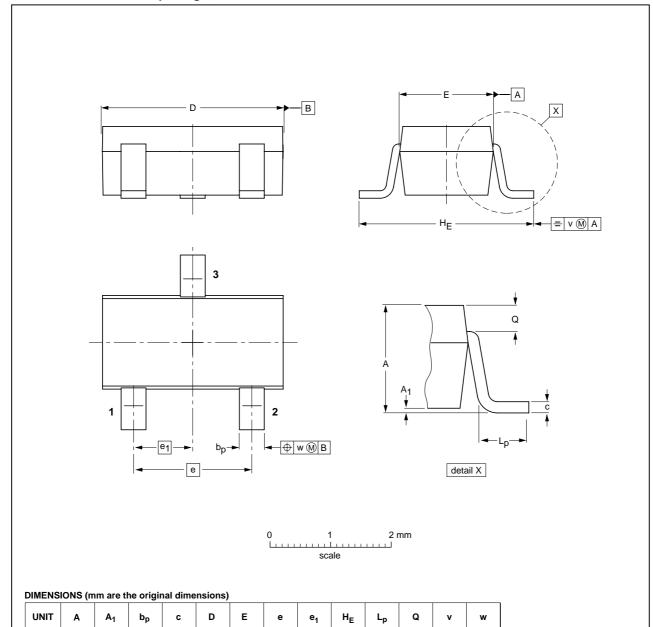
	REFERENCES			EUROPEAN	ISSUE DATE
IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE
		SC-89			05-07-28 06-03-16
	IEC		IEC JEDEC JEITA	IEC JEDEC JEITA	IEC JEDEC JEITA PROJECTION

NPN resistor-equipped transistors; R1 = 4.7 k Ω , R2 = open

PDTC143T series

Plastic surface-mounted package; 3 leads

SOT346



OUTLINE		REFER	RENCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	JEITA	PROJECTION	ISSUE DATE
SOT346		TO-236	SC-59A		-04-11-11 06-03-16

1.9

0.6

0.33

0.2

0.2

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1.3

1.0

0.1

0.013

0.50

0.35

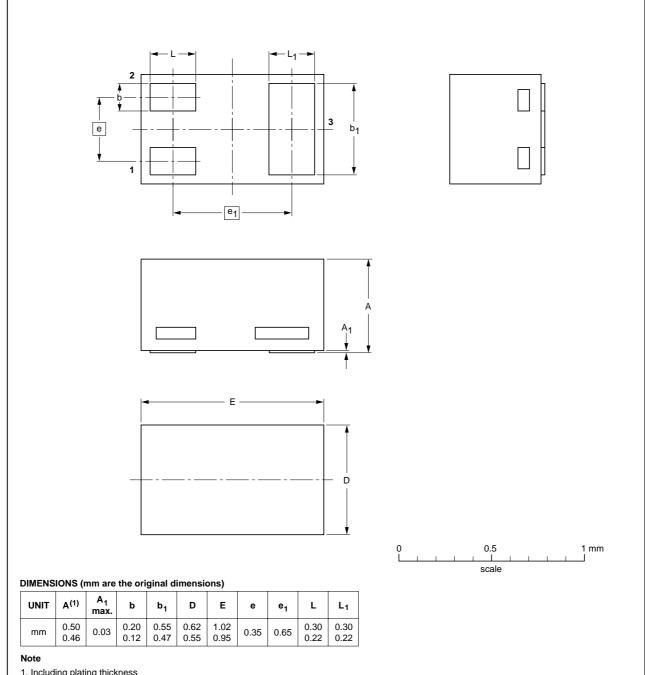
0.26

NPN resistor-equipped transistors; $R1 = 4.7 \text{ k}\Omega$, R2 = open

PDTC143T series

Leadless ultra small plastic package; 3 solder lands; body 1.0 x 0.6 x 0.5 mm

SOT883



1. Including plating thickness

OUTLINE		REFER	RENCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	JEITA	PROJECTION	ISSUE DATE
SOT883			SC-101		03-02-05 03-04-03

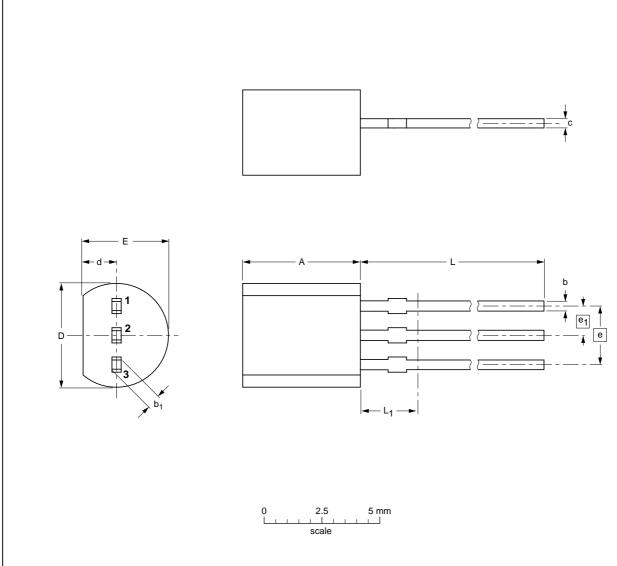
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NPN resistor-equipped transistors; R1 = 4.7 k Ω , R2 = open

PDTC143T series

Plastic single-ended leaded (through hole) package; 3 leads

SOT54



DIMENSIONS (mm are the original dimensions)

UNIT	Α	b	b ₁	С	D	d	E	е	e ₁	L	L ₁ ⁽¹⁾ max.
mm	5.2 5.0	0.48 0.40	0.66 0.55	0.45 0.38	4.8 4.4	1.7 1.4	4.2 3.6	2.54	1.27	14.5 12.7	2.5

Note

1. Terminal dimensions within this zone are uncontrolled to allow for flow of plastic and terminal irregularities.

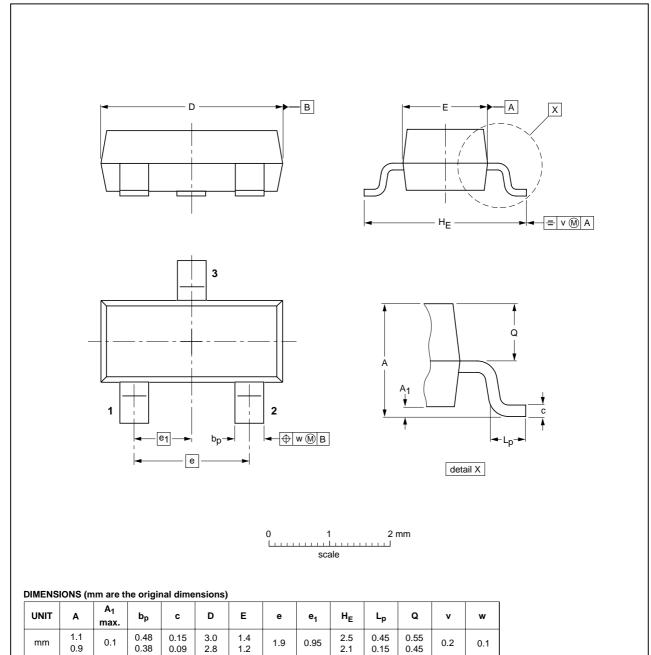
OUTLINE		REFER	REFERENCES			ISSUE DATE
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE
SOT54		TO-92	SC-43A			-04-06-28 04-11-16

NPN resistor-equipped transistors; R1 = 4.7 k Ω , R2 = open

PDTC143T series

Plastic surface-mounted package; 3 leads

SOT23



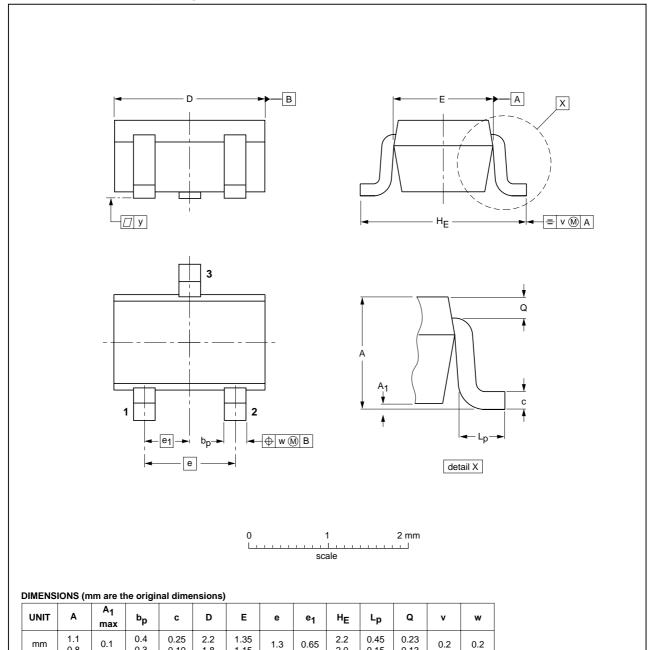
OUTLINE		REFER	EUROPEAN	ICCUE DATE			
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE	
SOT23		TO-236AB				-04-11-04- 06-03-16	

NPN resistor-equipped transistors; $R1 = 4.7 \text{ k}\Omega$, R2 = open

PDTC143T series

Plastic surface-mounted package; 3 leads

SOT323



OUTLINE		REFER	EUROPEAN	ISSUE DATE			
VERSION	IEC	JEDEC	JEITA	PROJECTION		ISSUE DATE	
SOT323			SC-70			-04-11-04 06-03-16	

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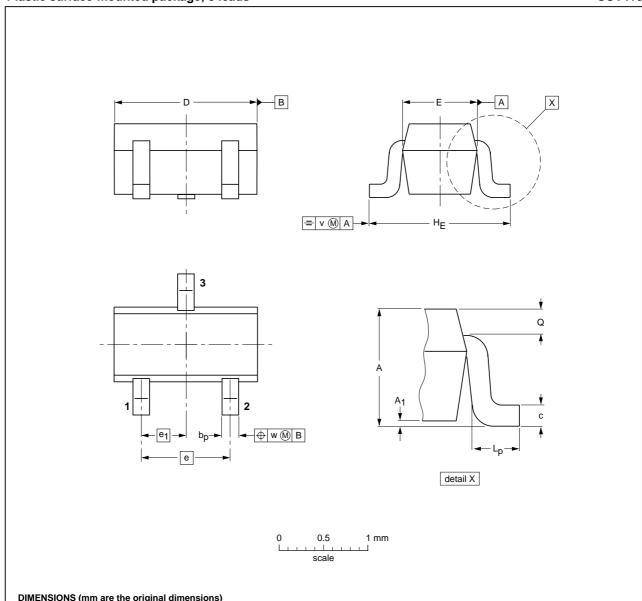
0.3

NPN resistor-equipped transistors; $R1 = 4.7 \text{ k}\Omega$, R2 = open

PDTC143T series

Plastic surface-mounted package; 3 leads

SOT416



DIMENSIONS	(mm are	the original	dimensions)
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U	NIT	Α	A ₁ max	bp	С	D	E	е	e ₁	HE	Lp	ø	v	w
n	nm	0.95 0.60	0.1	0.30 0.15	0.25 0.10	1.8 1.4	0.9 0.7	1	0.5	1.75 1.45	0.45 0.15	0.23 0.13	0.2	0.2

OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE
SOT416			SC-75			04-11-04 06-03-16

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NPN resistor-equipped transistors; R1 = 4.7 k Ω , R2 = open

PDTC143T series

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

Notes

- 1. Please consult the most recently issued document before initiating or completing a design.
- 2. The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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Contact information

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